CMOS Digital Integrated Circuits Silicon Monolithic

74HC175D

1. Functional Description

Quad D-Type Flip-Flop with Clear

2. General

The 74HC175D is a high speed CMOS D-TYPE FLIP FLOP fabricated with silicon gate C2MOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

Information signals applied to D inputs are transferred to the Q and \overline{Q} outputs on the positive going edge of the clock pulse.

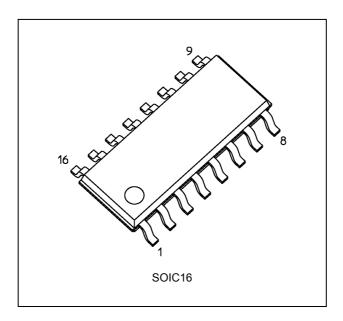
When the \overline{CLR} input is held low, the Q outputs are at the low logic level and the \overline{Q} outputs are at the high logic level independent of the other inputs.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

3. Features

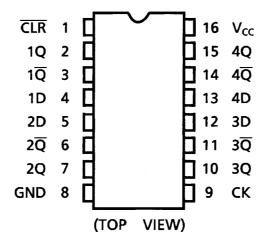
- (1) High speed: $f_{MAX} = 63 \text{ MHz}$ (typ.) at $V_{CC} = 5 \text{ V}$
- (2) Low power dissipation: $I_{CC} = 4.0 \mu A \text{ (max)}$ at $T_a = 25 \text{ °C}$
- (3) Balanced propagation delays: $t_{PLH} \approx t_{PHL}$
- (4) Wide operating voltage range: $V_{CC(opr)} = 2.0 \text{ V}$ to 6.0 V

4. Packaging

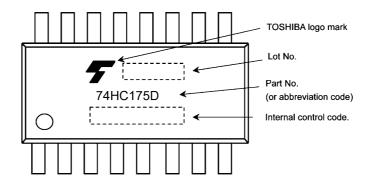




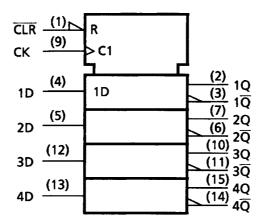
5. Pin Assignment



6. Marking



7. IEC Logic Symbol



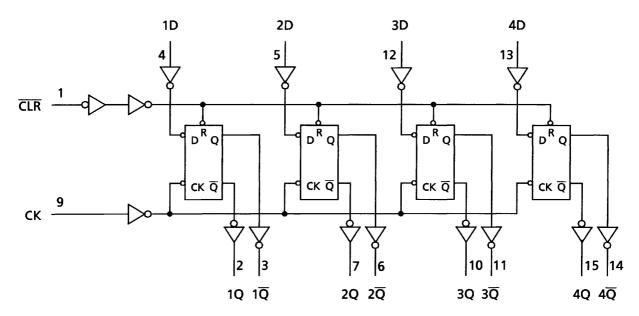
8. Truth Table

	Inputs			puts	Function		
CLR	D	СК	Q	Ια	Function		
L	Х	Х	L	Н	Clear		
Н	L		L	Н	_		
Н	Н		Н	L	_		
Н	Х		Qn	\overline{Q}_n	No Change		

X: Don't care



9. System Diagram



10. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Note	Rating	Unit
Supply voltage	V _{CC}		-0.5 to 7.0	V
Input voltage	V _{IN}		-0.5 to V _{CC} + 0.5	V
Output voltage	V _{OUT}		-0.5 to V _{CC} + 0.5	V
Input diode current	I _{IK}		±20	mA
Output diode current	I _{OK}		±20	mA
Output current	I _{OUT}		±25	mA
V _{CC} /ground current	I _{CC}		±50	mA
Power dissipation	P _D	(Note 1)	500	mW
Storage temperature	T _{stg}		-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: P_D derates linearly with -8 mW/°C above 85 °C

11. Operating Ranges (Note)

Characteristics	Symbol	Test Condition	Rating	Unit
Supply voltage	V _{CC}	ı	2.0 to 6.0	V
Input voltage	V _{IN}	I	0 to V _{CC}	V
Output voltage	V _{OUT}		0 to V _{CC}	V
Operating temperature	T _{opr}		-40 to 125	°C
Input rise and fall times	t _r ,t _f		0 to 50	μS

Note: The operating ranges must be maintained to ensure the normal operation of the device. Unused inputs must be tied to either V_{CC} or GND.



12. Electrical Characteristics

12.1. DC Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	ı	V _{CC} (V)	Min	Тур.	Max	Unit
High-level input voltage	V _{IH}	_		2.0	1.50	_	_	V
				4.5	3.15	_	_	
				6.0	4.20	_	_	
Low-level input voltage	V _{IL}	_		2.0	_	_	0.50	V
				4.5	_	_	1.35	
				6.0			1.80	
High-level output voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA	2.0	1.9	2.0	_	V
				4.5	4.4	4.5	_	
				6.0	5.9	6.0	_	
			I _{OH} = -4 mA	4.5	4.18	4.31	_	
			I_{OH} = -5.2 mA	6.0	5.68	5.80	_	
Low-level output voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA	2.0	_	0.0	0.1	V
				4.5	_	0.0	0.1	
				6.0	_	0.0	0.1	
			I _{OL} = 4 mA	4.5	_	0.17	0.26	
			I _{OL} = 5.2 mA	6.0		0.18	0.26	
Input leakage current	I _{IN}	V _{IN} = V _{CC} or GND		6.0	_		±0.1	μА
Quiescent supply current	I _{CC}	$V_{IN} = V_{CC}$ or GND		6.0	_		4.0	μΑ

12.2. DC Characteristics (Unless otherwise specified, T_a = -40 to 85 °C)

Characteristics	Symbol	Test Condition	١	V _{CC} (V)	Min	Max	Unit
High-level input voltage	V _{IH}	_		2.0	1.50	_	V
				4.5	3.15	_	
				6.0	4.20	_	
Low-level input voltage	V _{IL}	_		2.0	_	0.50	V
				4.5	_	1.35	
				6.0	_	1.80	
High-level output voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA	2.0	1.9	_	V
				4.5	4.4	_	
				6.0	5.9	_	
			$I_{OH} = -4 \text{ mA}$	4.5	4.13	_	
			$I_{OH} = -5.2 \text{ mA}$	6.0	5.63	_	
Low-level output voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA	2.0		0.1	V
				4.5	_	0.1	
				6.0	_	0.1	
			I _{OL} = 4 mA	4.5	_	0.33	
			I _{OL} = 5.2 mA	6.0	_	0.33	
Input leakage current	I _{IN}	$V_{IN} = V_{CC}$ or GND		6.0		±1.0	μА
Quiescent supply current	I _{CC}	$V_{IN} = V_{CC}$ or GND		6.0	_	40.0	μА



12.3. DC Characteristics (Unless otherwise specified, T_a = -40 to 125 °C)

Characteristics	Symbol	Test Condition	n	V _{CC} (V)	Min	Max	Unit
High-level input voltage	V _{IH}	_		2.0	1.50	_	V
				4.5	3.15	_	
				6.0	4.20	_	
Low-level input voltage	V _{IL}	_		2.0	_	0.50	V
				4.5	_	1.35	
				6.0	_	1.80	
High-level output voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA	2.0	1.9	_	V
				4.5	4.4	_	
				6.0	5.9	_	
			I _{OH} = -4 mA	4.5	3.7	_	
			I _{OH} = -5.2 mA	6.0	5.2	_	
Low-level output voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA	2.0	_	0.1	V
				4.5	_	0.1	
				6.0	_	0.1	
			I _{OL} = 4 mA	4.5	_	0.4	
			I _{OL} = 5.2 mA	6.0	_	0.4	
Input leakage current	I _{IN}	V _{IN} = V _{CC} or GND		6.0	_	±1.0	μА
Quiescent supply current	Icc	$V_{IN} = V_{CC}$ or GND		6.0	_	160.0	μА



12.4. Timing Requirements (Unless otherwise specified, $T_a = 25$ °C, Input: $t_f = t_f = 6$ ns)

Characteristics	Symbol	Test Condition	V _{CC} (V)	Тур.	Limit	Unit
Minimum pulse width	$t_{w(L)}, t_{w(H)}$	_	2.0	_	75	ns
(CK)			4.5	_	15	
			6.0	_	13	
Minimum pulse width	t _{w(L)}	_	2.0	_	75	ns
(CLR)			4.5	_	15	
			6.0	_	13	1
Minimum setup time	t _S	_	2.0	_	75	ns
			4.5	_	15	
			6.0	_	13	1
Minimum hold time	t _h	_	2.0	_	0	ns
			4.5	_	0	
			6.0	_	0	
Minimum removal time	t _{rem}	_	2.0	_	75	ns
			4.5	_	15	
			6.0	_	13	1
Clock frequency	f	_	2.0	_	6	MHz
			4.5	_	31]
			6.0	_	36	

12.5. Timing Requirements (Unless otherwise specified, T_a = -40 to 85 °C, Input: t_r = t_f = 6 ns)

Characteristics	Symbol	Test Condition	V _{CC} (V)	Limit	Unit	
Minimum pulse width	$t_{w(L)},t_{w(H)}$	_	2.0	95	ns	
(CK)			4.5	19		
			6.0	16		
Minimum pulse width	t _{w(L)}	_	2.0	95	ns	
(CLR)			4.5	19		
			6.0	16		
Minimum setup time	t _S	_	2.0	95	ns	
			4.5	19		
			6.0	16		
Minimum hold time	t _h	_	2.0	0	ns	
			4.5	0		
			6.0	0		
Minimum removal time	t _{rem}	_	2.0	95	ns	
			4.5	19		
			6.0	16		
Clock frequency	f	_	2.0	5	MHz	
			4.5	25		
			6.0	29		



12.6. Timing Requirements (Unless otherwise specified, T_a = -40 to 125 °C, Input: t_r = t_f = 6 ns)

Characteristics	Symbol	Test Condition	V _{CC} (V)	Limit	Unit
Minimum pulse width	$t_{w(L)}, t_{w(H)}$	_	2.0	110	ns
(CK)			4.5	22	
			6.0	19	
Minimum pulse width	t _{w(L)}	_	2.0	110	ns
(CLR)			4.5	22	
			6.0	19	
Minimum setup time	t _S	_	2.0	110	ns
			4.5	22	
			6.0	19	
Minimum hold time	t _h	_	2.0	0	ns
			4.5	0	
			6.0	0	
Minimum removal time	t _{rem}	_	2.0	110	ns
			4.5	22	
			6.0	19	
Clock frequency	f	_	2.0	4	MHz
			4.5	20	
			6.0	24	

12.7. AC Characteristics (Unless otherwise specified, $C_L = 15$ pF, $V_{CC} = 5$ V, $T_a = 25$ °C, Input: $t_r = t_f = 6$ ns)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Output transition time	t _{TLH} ,t _{THL}	_	_	4	8	ns
Propagation delay time (CK-Q, \overline{Q})	t _{PLH} ,t _{PHL}	1		16	24	ns
Propagation delay time (CLR-Q, Q)	t _{PLH} ,t _{PHL}	_	_	13	21	ns
Maximum clock frequency	f _{MAX}	_	36	63	_	MHz



12.8. AC Characteristics (Unless otherwise specified, C_L = 50 pF, T_a = 25 °C, Input: t_r = t_f = 6 ns)

Characteristics	Symbol	Note	Test Condition	V _{CC} (V)	Min	Тур.	Max	Unit
Output transition time	t _{TLH} ,t _{THL}		_	2.0	_	30	75	ns
				4.5	_	8	15	
				6.0	_	7	13	
Propagation delay time (CK-Q, $\overline{\mathbf{Q}}$)	t _{PLH} ,t _{PHL}		_	2.0	_	70	140	ns
			4.5	_	19	28		
				6.0	_	16	24	
Propagation delay time	t _{PLH} ,t _{PHL}	_	2.0	_	50	125	ns	
$(\overline{CLR}-Q,\overline{Q})$				4.5	_	16	25	
				6.0	_	12	22	
Maximum clock frequency	f _{MAX}		_	2.0	6	14	_	MHz
				4.5	31	53	_	
				6.0	36	63	_]
Input capacitance	C _{IN}		_		_	3	_	pF
Power dissipation capacitance	C _{PD}	(Note 1)	_		_	5		pF

Note 1: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation.

 $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}/4 \text{ (per F/F)}$

And the total C_{PD} when n pcs of latch operate can be gained by the following equation.

 C_{PD} (total) = 32 + 21 × n

12.9. AC Characteristics (Unless otherwise specified, $C_L = 50$ pF, $T_a = -40$ to 85 °C, Input: $t_r = t_f = 6$ ns)

Characteristics	Symbol	Test Condition	V _{CC} (V)	Min	Max	Unit
Output transition time	t _{TLH} ,t _{THL}	_	2.0	_	95	ns
			4.5	_	19	
			6.0	_	16	
Propagation delay time (CK-Q, $\overline{\overline{\mathbf{Q}}}$)	t _{PLH} ,t _{PHL}	_	2.0	_	175	ns
			4.5		35	
			6.0		30	
Propagation delay time	t _{PLH} ,t _{PHL}		2.0	_	160	ns
$(\overline{CLR}-Q,\overline{Q})$			4.5	_	32	
			6.0	_	27	
Maximum clock frequency	f _{MAX}		2.0	5	_	MHz
			4.5	25		
			6.0	29	_	



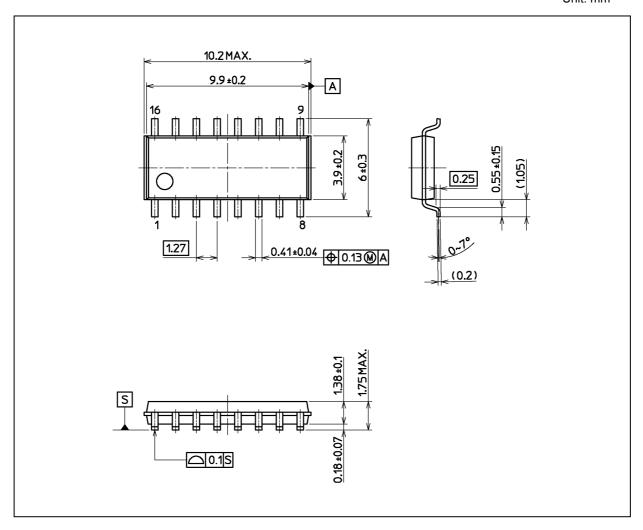
12.10. AC Characteristics (Unless otherwise specified, C_L = 50 pF, T_a = -40 to 125 °C, Input: t_r = t_f = 6 ns)

Characteristics	Symbol	Test Condition	V _{CC} (V)	Min	Max	Unit
Output transition time	t _{TLH} ,t _{THL}	_	2.0	_	110	ns
			4.5	_	22	
			6.0	_	19	
Propagation delay time (CK-Q, $\overline{\mathbf{Q}}$)	t _{PLH} ,t _{PHL}	_	2.0	_	210	ns
			4.5	_	42	
			6.0	_	36	
Propagation delay time ($\overline{\text{CLR}}$ -Q, $\overline{\overline{\text{Q}}}$)	t _{PLH} ,t _{PHL}	1	2.0	_	190	ns
			4.5	_	38	
			6.0	_	32	
Maximum clock frequency	f _{MAX}	_	2.0	4	_	MHz
			4.5	20	_]
			6.0	24	_]



Package Dimensions

Unit: mm



Weight: 0.15 g (typ.)

	Package Name(s)
Nickname: SOIC16	



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